

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

| Supplier<br>Nexperia B.V.<br>Name of Laboratory |                             | User Part Number                                     |             |           |            |           |  |
|---|-----------------------------|--|-------------|-----------|------------|-----------|--|
|   |                             | PMEG2005CT   |             |           |            |           |  |
|   |                             | Part Description                                     |             |           |            |           |  |
|   |                             | Nexperia DHAM  | Schottky    |           |            |           |  |
| Assembly reliability labs                       |                             | SMD package  |             |           |            |           |  |
| Based on AEC-Q101 Test                          |                             | Test Conditions                                      | Duration    | # Lots    | # Quantity | # Rejects |  |
|   | TEST                        |  |             |           |            |           |  |
|   | Pre- and Post-Stress        |  |             |           |            |           |  |
| # E1  | Electrical Test             | Tamb = 25 °C   | N/A         | see below | all parts  | see below |  |
|   |                             | JESD22-A113  |             |           |            |           |  |
|   |                             | Bake Tamb = 125 °C                                   | 24 hours    |           |            |           |  |
|   | PC                          | Soak Tamb = 85 °C, RH = 85%                          | 168 hours   |           |            |           |  |
| # A1  | Preconditioning             | Reflow soldering                                     | 3 cycles    | 810       | 58300      | 0         |  |
|   |                             | MIL-STD-750-1  |             |           |            |           |  |
|   | HTRB                        | M1038 Method A                                       |             |           |            |           |  |
|   | High Temperature Reverse    | Tj = Tjmax, Vr = 100% of max. datasheet              |             |           |            |           |  |
| # B1  | Bias                        | reverse voltage <sup>[1]</sup>                       | 1000 hours  | 116       | 9280       | 0         |  |
|   | тс                          | JESD22-A104  |             |           |            |           |  |
| # 44  | Temperature Cycling         | -65 °C to Tjmax, not to exceed 150°C                 | 1000 evelee | 170       | 12600      | 0         |  |
| # A4  | remperature cycling         | • '  | 1000 cycles | 170       | 13600      | U         |  |
|   | AC                          | JESD22-A102<br>Tamb = 121 °C, RH = 100 %             |             |           |            |           |  |
| # A3 alt  | Autoclave                   | Pressure = 205 kPa (29.7 psia)                       | 96 hours    | 170       | 13600      | 0         |  |
| AS all  | Autociave                   | 11essure = 205 ki a (25.7 psia)                      | 96 Hours    | 170       | 13600      | U         |  |
|   | H3TRB                       | JESD22-A101  |             |           |            |           |  |
|   | High Humidity High          | Tamb = 85 °C, RH = 85%, VR = 80 % of                 |             |           |            |           |  |
| # A2 alt  |                             | rated reverse voltage <sup>[1], [2]</sup>            | 1000 hours  | 170       | 13600      | 0         |  |
| # AZ dit  | Temperature Neverse Blas    | MIL-STD-750 Method 1037                              | 1000 110013 | 170       | 13000      | 0         |  |
|   | IOL                         | ton = toff, devices powered to insure $\Delta T_i$ = |             |           |            |           |  |
| # A5  | Intermittent Operating Life |  | 1000 hours  | 170       | 13600      | 0         |  |
| + A3  | Operating Life              | 100 0 .o. 10000 cycles                               | 1000 Hours  | 1/0       | 13000      | U         |  |
|   | RSH                         | JESD22-A111  |             |           |            |           |  |
| # C8  | Resistance to Solder Heat   | 260 °C ± 5 °C  | 10 s        | 130       | 3900       | 0         |  |
|   | SD                          |  | 10.3        | 130       | 3300       |           |  |
|   |                             |  |             |           |            |           |  |

<sup>[1]</sup> The physical limitations of Schottky diodes have to be considered (thermal runaway).

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia  |            |          |         |                    |            |
| DHAM      | Schottky   | 9280     | 0       | 0.46               | 2.19E+09   |

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<sup>[2]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.